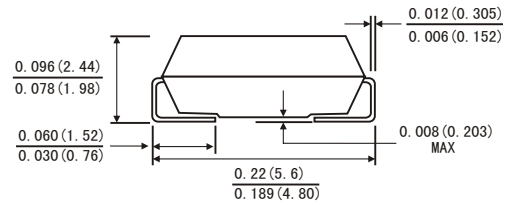
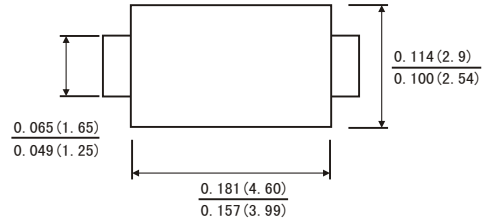


FEATURES

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Construction utilizes void-free molded plastic technique
- For surface mounted applications
- Built-in strain relief, ideal for automated placement
- High temperature soldering guaranteed: 260 °C/10 seconds at terminals
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC



SMA(DO-214AC)



Dimensions in inches and (millimeters)

MECHANICAL DATA

- Case: JEDEC DO-214AC molded plastic over glass passivated chip
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- *Mounting Position: Any*
- Weight: 0.002 oz., 0.064 g

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %

Parameter	Symbols	S2A	S2B	S2D	S2G	S2J	S2K	S2M	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_a = 65\text{ °C}$	$I_{F(AV)}$	2							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	60							A
Maximum Instantaneous Forward Voltage at 2 A	V_F	1.1							V
Maximum DC Reverse Current $T_a = 25\text{ °C}$ at Rated DC Blocking Voltage $T_a = 125\text{ °C}$	I_R	5 50							μA
Typical Junction Capacitance ¹⁾	C_j	30							pF
Typical Thermal Resistance ²⁾	$R_{\theta JA}$	50							°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							°C

1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

2) Thermal resistance from junction to ambient at 0.375" (9.5 mm) lead length, P.C.B. mounted

Fig.1 Forward Current Derating Curve

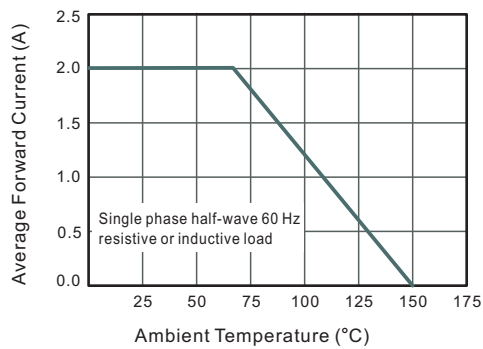


Fig.2 Typical Instantaneous Reverse Characteristics

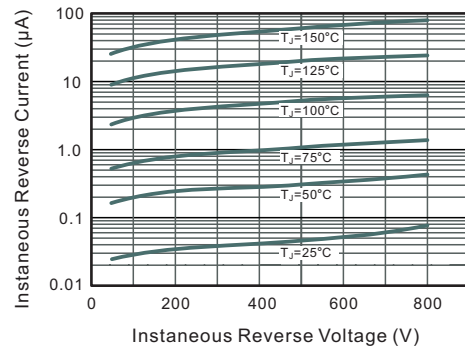


Fig.3 Typical Forward Characteristic

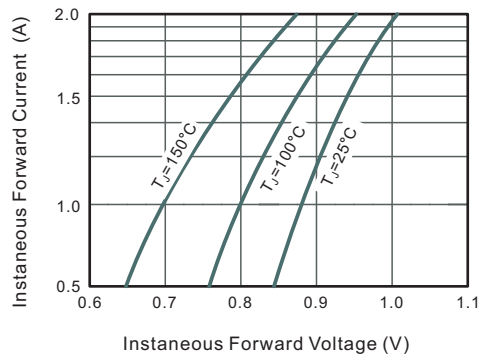


Fig.4 Typical Junction Capacitance

